

LINQBOND LB-FL501



Fill Encapsulant for DnF applications

- Fill Encapsulant
- Low CTE α_1
- Easy flow, Low Viscosity

LINQBOND LB-FL501 is a high-performance, one-component **fill** epoxy encapsulant specifically designed for demanding semiconductor applications. Formulated with a low thermal expansion coefficient (CTE1: 23.2 ppm/°C, CTE2: 76.6 ppm/°C), LB-FL501 provides exceptional thermal stability and protects sensitive components from mechanical stress and environmental factors. Its excellent operability combined with a viscosity of **37,000 cps** at 25°C ensures **easy handling and precise dispensing**, while its strong adhesion and chemical resistance contribute to the overall reliability of electronic assemblies.

LINQBOND LB-FL501 epoxy encapsulant offers superior resistance to a wide range of chemicals and solvents, safeguarding components from degradation. Additionally, LB-FL501 exhibits **outstanding heat shock resistance**, making it suitable for applications that experience rapid temperature fluctuations. Typical applications include **IC memory cards**, chip carriers, hybrid circuits, chip-on-board, multi-chip modules, BGA, and pin grid arrays. It comes in 5, 10, 30 and 50cc syringes.

Cure Schedule

- 30 minutes @ 135°C plus 90 minutes @ 175°

Uncured properties

Property	Value	Unit
Appearance (Visual inspection)	Black	–
Chemistry	Epoxy	-
Viscosity at 25 °C (Brookfield DV)	37000	cps
Density	1.8	g/cm3

Cured properties

Property	Value	Unit
Coefficient of Thermal Expansion α_1	23	ppm/°C
Coefficient of Thermal Expansion α_2	77	ppm/°C
Glass Transition Temperature	180	°C
Chloride (Cl ⁻)	5	ppm
Sodium (Na ⁺)	5	ppm

Europe

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South East Asia

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Curing Conditions:

- 30 minutes @ 135°C plus 90 minutes @ 175°C

These conditions serve as a reference only. Please establish the curing conditions based on the product's specific requirements.

Precautions:

1. This product needs to be stored at a freezer.
2. When the material is take out from refrigeration, thaw it first prior to use. Keep in an airtight container at room temperature. After thawing for at least 6 to 8 hours, open and then use.
3. The adhesive cannot be refrozen once exposed to room temperature.
4. Maintain a clean and ventilated workplace, using extraction trunks when necessary.
5. Wear appropriate protective equipment and minimize direct contact with the human body. Refer to the Material Safety Data Sheet (SDS) before use.

Please note that the provided information is based on available data and typical conditions. For specific applications and detailed test results, refer to the actual test data and conduct appropriate certifications.

Storage and Handling

Store and transport in a -40°C freezer. Keep away from fire and heat sources. It is strictly forbidden to store in outdoor environments.

Shelf life at -40 °C 183 days

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